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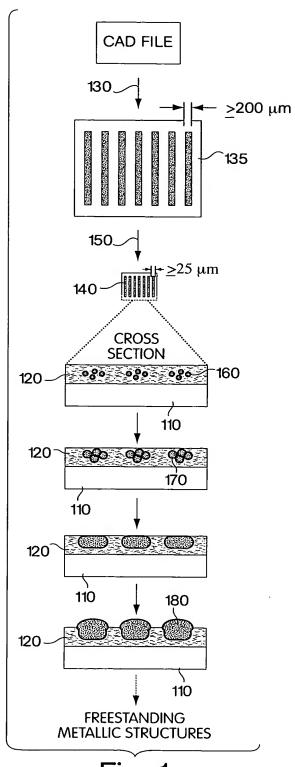


Fig. 1

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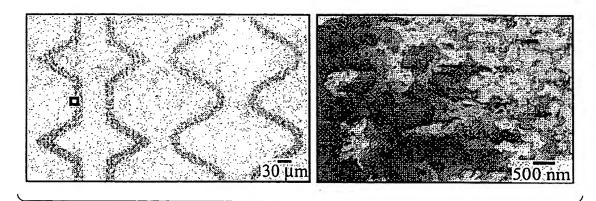


Fig. 2A

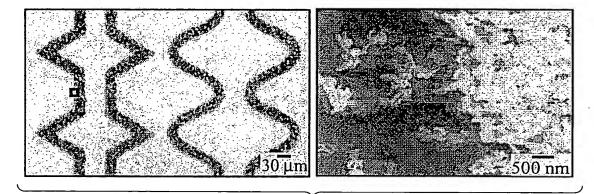


Fig. 2B

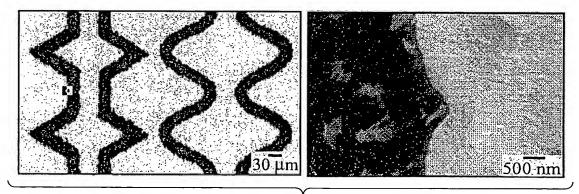


Fig. 2C

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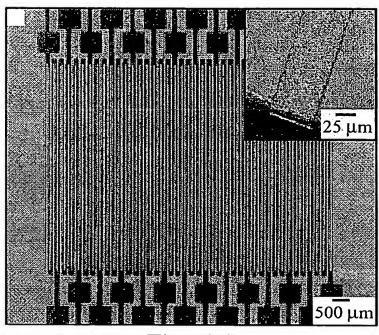


Fig. 3A

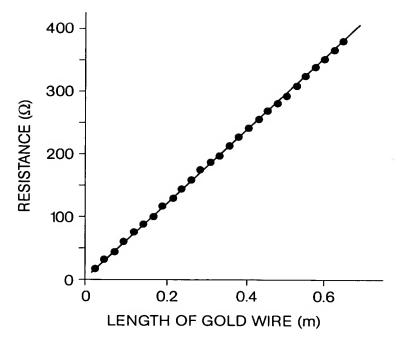


Fig. 3B

Fabrication of Metallic Microstructures via Exposure of Photosensitive etc. Deng et al.
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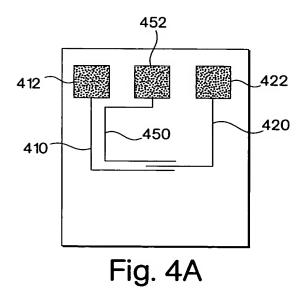
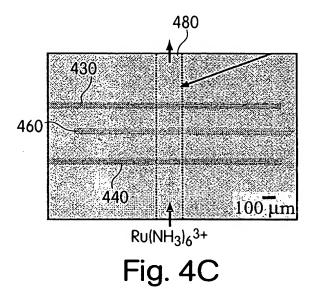


Fig. 4B

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200 100 0 Current (nA) -100 -200 -300 -400 -0.5 -0.4 -0.3 -0.2 -0.1 0 Potential vs. Ag/AgCl (V) Fig. 4D

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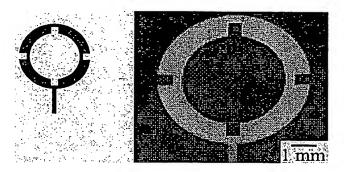


Fig. 5A

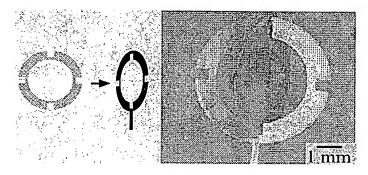


Fig. 5B

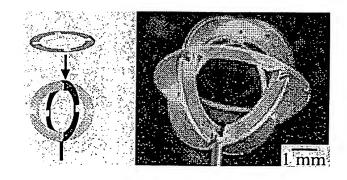
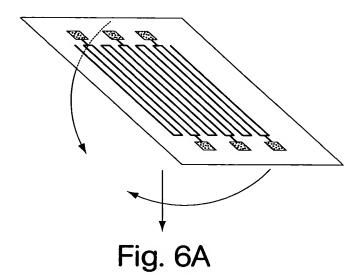


Fig. 5C

Fabrication of Metallic Microstructures via Exposure of Photosensitive etc.
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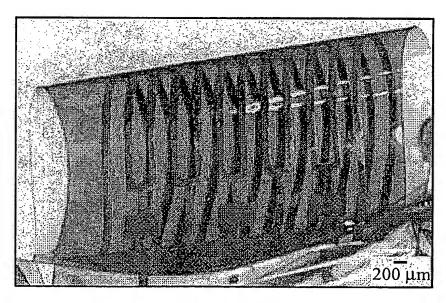


Fig. 6B

Fabrication of Metallic Microstructures via Exposure of Photosensitive etc.

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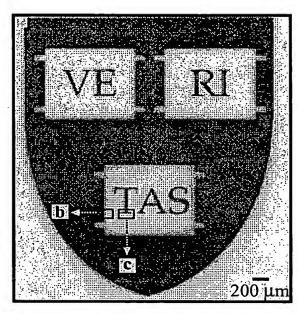


Fig. 7A

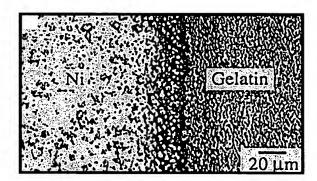


Fig. 7B

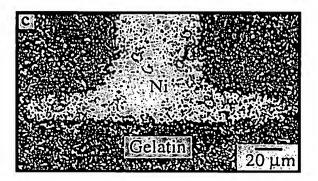


Fig. 7C

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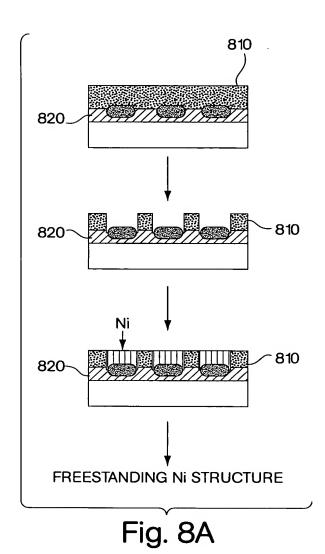


Fig. 8B